The Micromegas chambers for the ATLAS New Small Wheel upgrade

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on behalf of

the ATLAS Muon Collaboration

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Introduction

The New Small Wheel

One of the most important upgrade of the Long Shutdown 2

Expected to work at

- ~ 15 kHz/cm² @ | ŋ | ~ 2.7
- ~ 500-600 Hz/cm² @ | η | ~ 1.3

=>MDTs efficiency reduction at high rate to cope with the High Lumosity LHC Phase

Single muon trigger efficiency - P_T resolution better than 15% @ 1 TeV - Huge fake trigger rate in the endcap region

1 mrad + 100 µm (single hit) resolution needed



Pseudorapidity range covered:

1.3 < | ŋ | < 2.7

The New Small Wheel - detectors

MicroMegas with Resistive Strips technology as a Precision Tracker

- Spatial resolution ~ 100 μm
- Resistive anode strips to suppress discharge influence on efficiency
- Compromise to reach the rate capability required
- Providing online segments for trigger





Small Thin Gap Chambers as a primary trigger in the End Cap

- Bunch iD with good timing resolution
- Online track vector with <1 mrad resolution
- pads: region of interest
- strips: track info (strip pitch 3.2 mm)
- wire groups: coarse azimuthal coordinate

see Dennis Pudzha's talk

The New Small Wheel - substructure



for the 2 wheels

The New Small Wheel - MicroMegas modules

Each module is composed by 4 layers - 3 or 5 PCB (see next slide)



2 planes with parallel strips -> eta precision coordinate

2 planes with 1.5° inclined strips -> 2nd (phi) coordinate through stereo strips

Quadruplet:

128 µm amplification gap, 5 mm drift gap

- 2 readout panels (eta or stereo) with double readout side
- 1 double drift panel (inner) with 2 meshes
- 2 single drift panels (outer) with 1 mesh each
- \rightarrow 32 different types of readout boards \rightarrow 2176 PCB boards produced



The New Small Wheel - MM Resistive Anode





PCB structure



Board dimensions: from 45x30 up to 45x220 cm²

- 1022 strips/boards
- Strip width: 300 µm
- Strip pitch: 425/450 μm
- Pillar distance: 7.0 mm
- Readout strips pitch: 425 or 450 μm
- Pillar size: 1000x200 µm
- Pillars height: 128 µm

Resis	stivity
~800	kΩ/□

Alignment requirements: 30 μm RMS in η 80 μm RMS in z

Modules Production

Modules Production - Construction Cycle

Poster session: Irakli Minashvili



Modules Production - Construction Cycle: cleaning



3. Ventilated Oven-Drying at ~40°



procedures:

readout panels





Production remnants removed

Micropolishing cleaning procedure:

1. Hard and soft brushes with detergents (CIF - gentle polish action) 2. Washing with hot and demineralized water

Modules Production - Mechanical tests on RO panels and assembled quadruplets

Mech Precision & Planarity

LM1 (ex) panel to panel alignment within a module:





LM2 final module planarity (RMS): 117 μ m

- 78.1

- 78.0

77.9

- 77.8

- 77.7

77.6





Modules Production - HV conditioning: ==> first HV stability issues observed



Evidences of effects of low resistivity on the HV stability

a SM1 MM chamber after 2 months of irradiation @ GIF++

studies on correlations between unstable sections and low resisitivity PCBs

Solutions applied

MM validation & integration - HV/irradiation studies



80 kHz/cm² 30 kHz/cm²

Fig. 8a, from D. Pfeiffer et al., NIM_A_866(2017)91-103

HV stability - Causes

Local discharges close to strips interconnections





Strong discharges along the piralux rim (closest point to the HV distribution line) and interconnections found after the long term irradiation studies at GIF++

This triggered investigations on the resistance of the strips pattern to the HV line and strip resistivity

Modules Production - Electrical tests on RO panels before assembly



How to increase the HV stability - Passivation



How to increase the HV stability - Passivation

A "good" sector: HV>565 V, spike rate < 6/min



How to increase the HV stability - Gas Mixtures

New gas mixtures have been studied (standard Ar/CO_2 93/7%):

Ar/CO₂80/20%

Ar/CO₂/C₄H₁₀ 93/5/2%

The isobutane seems to be really effective



L1L8

Ageing studies are ongoing at the GIF++ in order to check the impact of using isobutane on the long term operation of the detector.

Timing issue: most likely not feasible within the installation schedule.



MM Validation and Integration of Double Wedges @ CERN

MM validation & integration - Workflow

General scheme of MM integration into Double Wedges











source platforms glueing and rasnik mask test



MM validation & integration - first DW A14 PASSIVATED



MM validation & integration - first DW A14 PASSIVATED



Measured average Tracking efficiencies per layer for the A14 Small DW:

in average well above 90% IP side lower then HO (gas flow/RH?)

==> A14 is a non passivated Small DW

Blue: measured track efficiency at the Cosmics Stand for the Small DW A14 (Wheel A). First VMM chip version used.

Green: measured track efficiency for SM2-M1 at H8 testbeam @ CERN in summer 2018.

The A14 efficiency is higher than the one measured (a) H8 (higher thresholds because of VMM noise).

IP SM1+SM2	Efficiency Cosmic Muons)		HO SM1+SM2	Efficiency (Cosmic Muons)	
Layer 1	85.4	%	Layer 1	98.1	%
Layer 2	89.1	%	Layer 2	97.2	%
Layer 3	<mark>84</mark> .1	%	Layer 3	92.8	%
Layer 4	85.3	%	Layer 4	90.8	%

First attempt to Sector (MM +sTGC) installation on NJD





- Gas leak tests & flushing
- HV: confirm behavior
- Baselines, thresholds, noise runs, calibrations
 Pulsing & patterns
 Trigger onth validation

- Few cosmics for sign-off, to volocate whole readout+chamber chain
 System tests: latency, high rate, Sector logic











Stat	us of ch	ambers	production	ı & DW inteç	gration	Double Wedges			Ber 1
	at CERN	ready for shipping	in preparation	missing for NSW-A/end of production	missing for NSW-C/end of production	completed (in preparation)			
SM1	18	4	2	/	8 / June	7 (1)		Mar n	
SM2	18	2	4	/	8 / June		WE ZE		Nº CON
LM1	9	0	2	5 / April	16/Decem.	3 (2)	HOUL		
LM2	11	0	2	3 / April	16/Decem.			Sec.	- En
	first	sector	r A14 to b	be instal	led by th	ne end of F	ebruary.		

Second sector coming soon after

A14 Sector installed tonight!!!!!



Summary and conclusions

Micromegas technology has been chosen for the ATLAS NSW upgrade ==>to reach HL-LHC constraints as a main tracking detector

Large area resistive strips MM have been developed for the first time ==>(resolution + detector spark protection + rate capability compromise)

Main issue encountered: HV unstability

==> found to be correlated to low resistance of resistive strip anode

==> applied solutions

+ passivation in order to deactivate the region where R<0.8 M Ω

The HV stability is almost under control now ! Passivation played a fundamental role to get rid of the issue but in some cases significant loss of active area ==> several solutions under study (passivation with polyurethane, grinding, new foil production procedure)

Production of NSW-A:

+ 87,5% of modules produced + 10/16 sectors ready (+ 3 under integration)

Production of NSW-C:

+ 25% of modules produced

Integration activities @ CERN fully operational

•The first full sector (MM+sTGC) installed on the wheel A for testing the integration procedure! (A12-to be then removed) •The first final full sector (A14) installed tonight! •The second full sector being installed just after A14!

•On time to install the first wheel at the end of the year

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MM requirements and challenges

- 1. Strip alignment per each layer over O(m2)
 - 30 μm RMS in η
 - 80 µm RMS in z
- 2. Planarity within 100 μm RMS
- 3. Technological transfer to industry of Readout PCBs production at very high quality
- 4. HV Stability at high electric field (~50 kV/cm) on wide surfaces O(m2)

The New Small Wheel - MM Resistive Anode



PCB structure



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Modules Production - Electrical tests on RO panels before assembly









Dry cleaning, tests and alignment:

Remove dust with dedicated roller HV shorts check with MeshTool Gas leak test gap by gap Insert 10 Pins to align the FE boards Detector Assembly: Load Cells to balance the weight of panels on alignment pins

Then the panel is pushed towards the assembly structure



Modules Production - Construction Cycle: cleaning





The Mesh grids used for the ATLAS MM are **not flattened by calendering**.

They may present imperfections and produce discharges if pointing toward the resistive strips.

Polishing and cleaning procedure:

- 1. Wet sandpaper (2500) to remove defects
- 2. wet the mesh by hot water (40 45)° C
- 3. brush with degreaser solution
 - (10 g NGL in 1.5 l hot water) on both mesh face
- 4. wait 10' for the degreaser to act
- 5. rinse the two mesh faces with hot water and brush
- 6. rinse the two mesh with demineralized water

Mesh studies:

HV stability

Type (d-a µm)	Comment
18-45 N	Non calendered
18-45 C	Calendered
28-50 N	Non calendered
30-71 P	Non calendered; Manually polished
30-71 C	Calendered
30-80 C	Calendered

Experimental conditions

- 5.9 keV photons from a ^{55}Fe source
- photon rate ~ 100 Hz/cm²
- measured both peak amplitude and rate

Main results:

-> same gain reached at lower HV for smaller spacing mesh -> best results with **1. calendered 2. small spacing grid** Unfortunately not available at large enough surface Thus sanding applied to all NSW production







a calendered mesh





Efficiency

APV25 with samplings of 25 ns

LNF interface cards with **2 adiacent strips**

SM1 Cosmic stand



Trigger:

2 arrays of plastic scintillators

PMTs -> 50 Hz (25cm x 150 cm)

35 cm Fe to cut muons at ~0.5 GeV



	CS 20181123	BB5/vert 20190325	GIF 20190409	GIF 20190411	GIF 20190418	GIF 20190430	GIFnorad 20190502	GIF 20190509	GIFnorad 20190522	BB5/vert 20190529	BB5/vert 20190611	BB5/vert 20190612	BB5/vert 20190614	BB5/vert 20190625
L1L1 L1R2 L1R2 L1R3 L1R3 L1R4 L1R4 L1R4 L1R5 L2L1 L2R2 L2R2 L2R3 L2R3 L2R4 L2R4 L2R4 L2R5 L2R5														
L3L1 L3R1 L3R2 L3R2 L3R3 L3R4 L3R4 L3R4 L3R4 L3R5 L3R5 L4L1 L4R1 L4R2 L4R3 L4R3 L4R4 L4R4 L4R5 L4R5														

HV stability - Causes





Local dirt on the mesh





Strong discharges along the piralux rim and interconnections found after the long term irradiation studies at GIF++

> This triggered investigations on the resistance of the strips pattern

How to increase the HV stability - Resistive Paste

ESL Paste type

"Old" paste (same batch used in pre-series) : Resistivity ~1MΩ/sq. Good resistivity 12 foils done, then no more available...

"New" paste

Resistivity ~0.4-0.5MΩ/sq 70 foils... much worse

Resistive foils lamination

done through

in line 'pumice' (Al powder bath). manually with following steps

- Sandpaper 2500
- CIF cleaning
- Rinsing
- Mild micro-polishing bath



new paste

LS8

0 JAP

old paste

p [MQ/sq]

HV stability - Causes



Several measurements with a multimeter on lines parallel to the silverline

showed

1. no low resistance values along the line closer to the silver line (far from first interconnection line)

2. low periodic resistance values while getting closer to the first interconnection line

3. local defects can be also detected

How to increase the HV stability - Resistive Paste

New paste and foil production procedure under study.: 500 new foils produced in grade A/B by pressing at lower pressure and higher temperature Target mean value is 0.84MΩ/sq.

<u>Resistive foils categories criteria</u> Avergage resistivity 0.28 <R <2.6MΩ/sq Outlier criteria:

•99% of measured points 0.28 <R <2.6MΩ/sq: Grade A •95% of measured points within 0.28 <R <2.6MΩ/sq: Grade B •95% of measured points within 0.21 <R <3.4MΩ/sq: Grade B-

Last 150 foils made with a paste at higher resisitivity following the same procedure:

==> showed strong resistance increase (cracks?)

	Before	pressing	After pressing		
	Up [MΩ/sq]	Down [MΩ/sq]	Up [MΩ/sq]	Down [MΩ/sq]	
new 1- ③	1.25	1.92	>100	>100	
new 1-④	0.98	1.65	>100	>100	
new 2-2	0.90	1.15	13	8.2	
new 2-3	1.47	1.20	7.3	5.9	
old 2-3	0.62	0.69	2.9	12.2	



Standard procedure for gluing:

Pacolon
Pressure of 14 bar
Temperature of 170°C

NEW PRESSING Procedure:

Pacothane
Pressure of 12 bar
Temperature of 180°C

HV stability - Causes



Examples of discharges Interconnections close to the edge





- Resistive strips are screen-printed on a kapton support
- Average resisitivity are at the lower limits of acceptance
- Minimum Resistivity is often below the limit (0.28 M Ω / \Box)
- Interconnections on the resistive strip layout
 => locally lower resistivity
- Resistive strips layout is different between PCB types
- In many cases the discharges localized on resistive strips interconnection crossing the coverlay
- Some PCB types more affected than others
- e.g. LM1 both stereo and eta, SM1 stereo, not eta panels

How to increase the HV stability - additional curing tested





flakes



NaOH treatment

Pumice powder brushing

NaOH bath

Ethanol bath

were tried to remove dirt flakes around pillars. No clear response on the effectiveness

Polyurethane

Polyurethane is applied using a paintbrush(10-20 µm)

Dielectric constant 3-6 (Araldyte : ~4) RH absorption < 1% (same for Araldyte) Radiation hardness compatible to Araldyte



L3 L4 at 570 V

How to increase the HV stability - improve resistance









higher than aluminum

Main idea is to make the strips thinner in a region of ~ 1 cm in order to increase resistivity for the whole resistive stips panel

two approaches used:

grinding non-continuos areas along the coverlay
 --> doesn not solve isolated strips problems

2. uniform grinding --> good results!

How to increase the HV stability - improve resistance



@1cm from the coverlay:

- before grinding Res<1 $M\Omega$
- after grinding Res ~ 1-11 $M\Omega$

@ 1 cm from the coverlay after several grinding: Res ~ 2 $M\Omega$

@ 24 cm (1/4 of a panel) : Res ~ 5 $M\Omega$

@ 54 cm (1/2 of a panel): Res ~ 9 M Ω

MM validation & integration - Workflow

General scheme of MM integration into Double Wedges







MM validation & integration - Alignment

Proximity alignment lines



Optical fibers

Source platform





MM validation & integration - Electronics



MM validation & integration - NSW-A SDWs HV



MM validation & integration - HV/irradiation studies



MM validation & integration - Mechanical Integration











